

# Device Modeling Report

COMPONENTS:MAGNETIC CORE  
PART NUMBER:HS10  
MANUFACTURER:TDK



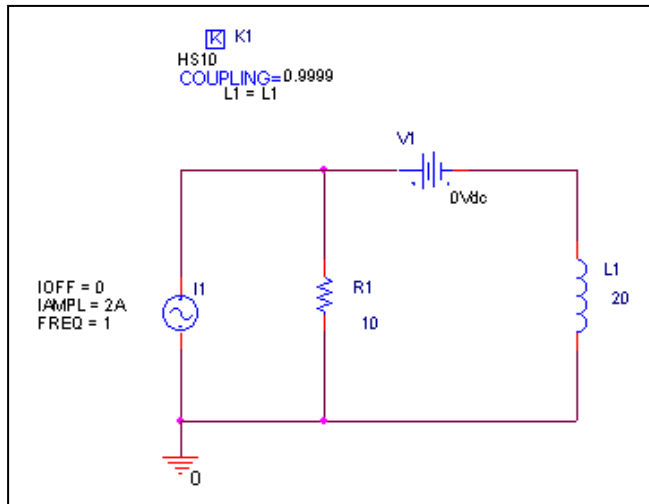
**Bee Technologies Inc.**

## MAGNETIC CORE

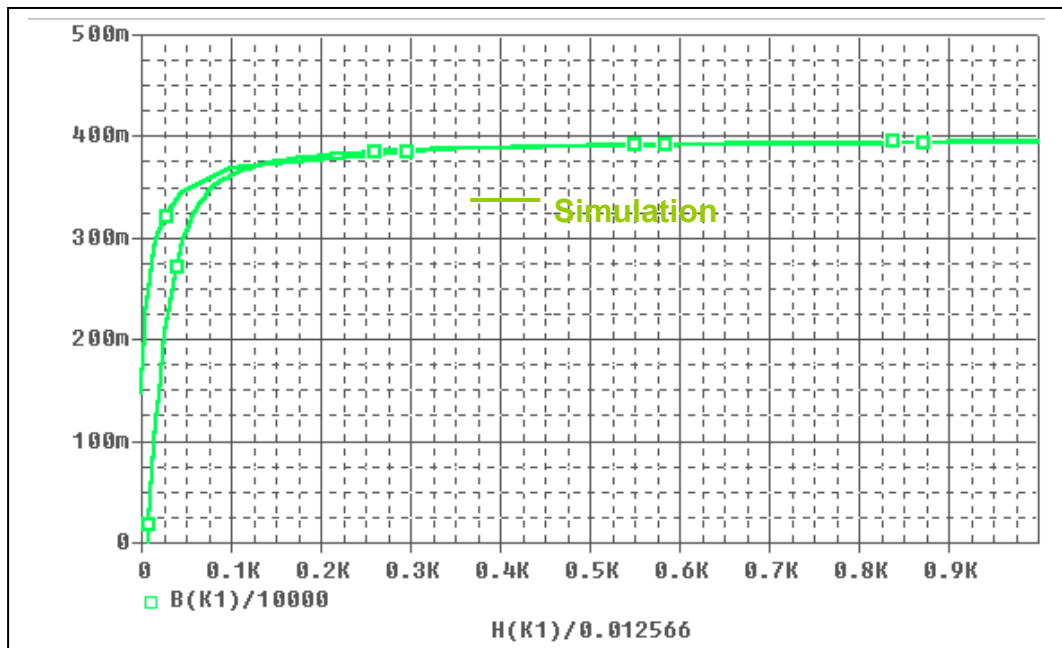
Pspice model parameter	Model description
A	thermal energy parameter
K	domain anisotropy parameter
C	domain flexing parameter
MS	magnetization saturation

# Hysteresis Curve Characteristics

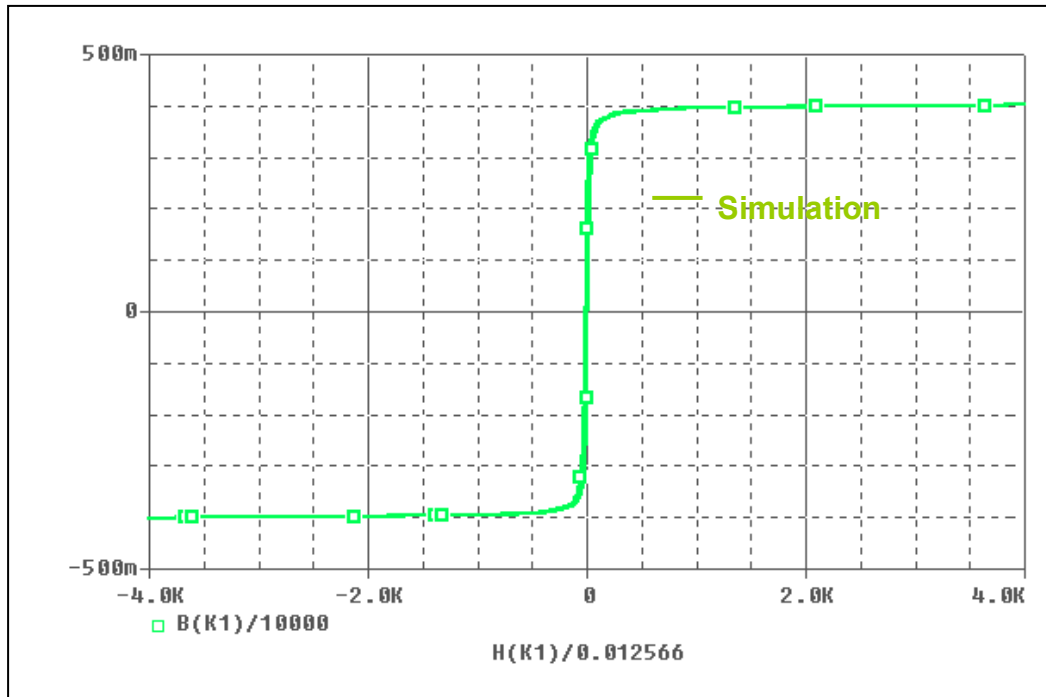
## Evaluation Circuit



## Simulation result



Simulation result



Comparison Table

H(A/m)	B(mT) Measurement	B(mT) Simulation	%Error
50	350	347.165	0.810
100	375	369.707	1.411
200	380	377.383	0.689
300	380	385.06	1.332
400	385	389.611	1.198
500	390	391.15	0.295
600	390	392.678	0.687
700	395	393.405	0.404
800	397	394.131	0.723
900	398	394.713	0.826
1000	400	395.103	1.224